

FIG.11

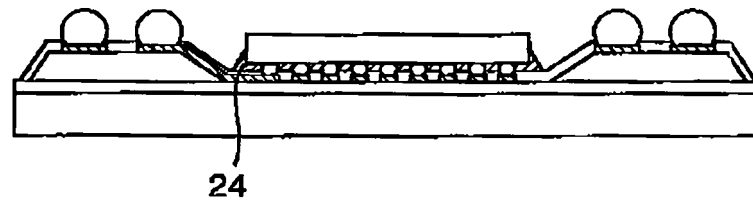


FIG.12

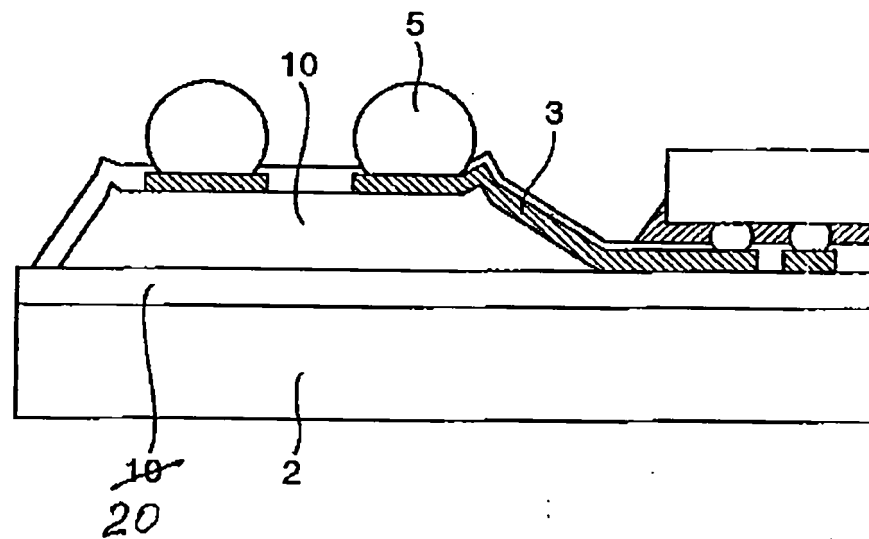


FIG.23A

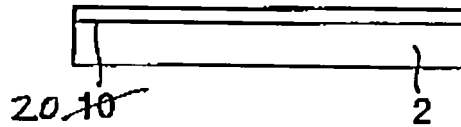


FIG.23B

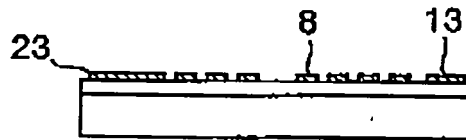


FIG.23C

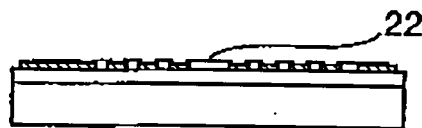


FIG.23D

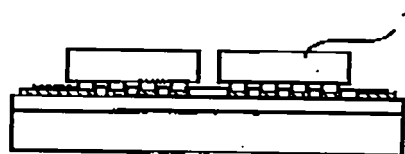


FIG.23E

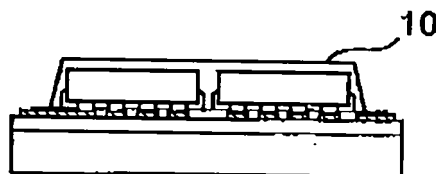


FIG.23F

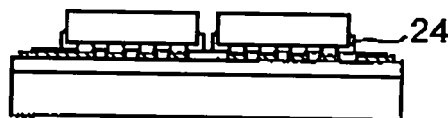


FIG.23G

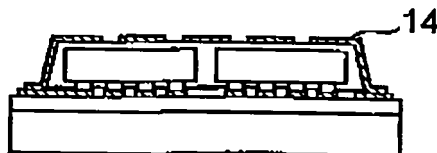


FIG.27

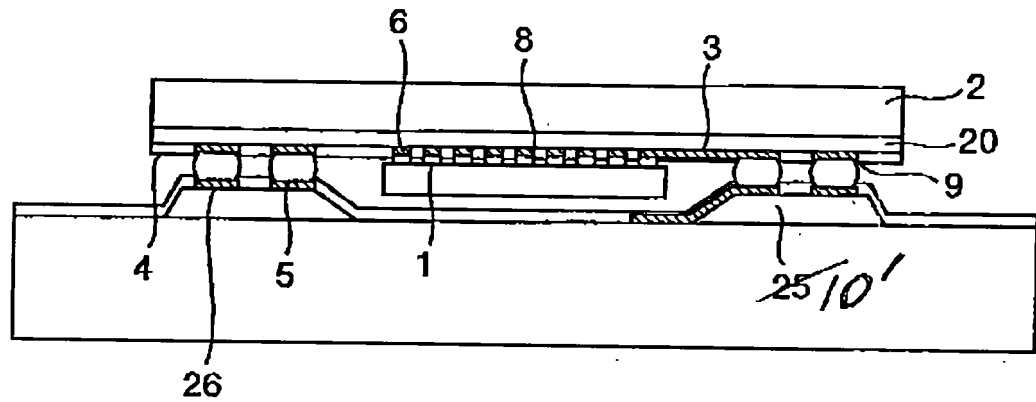


FIG.28

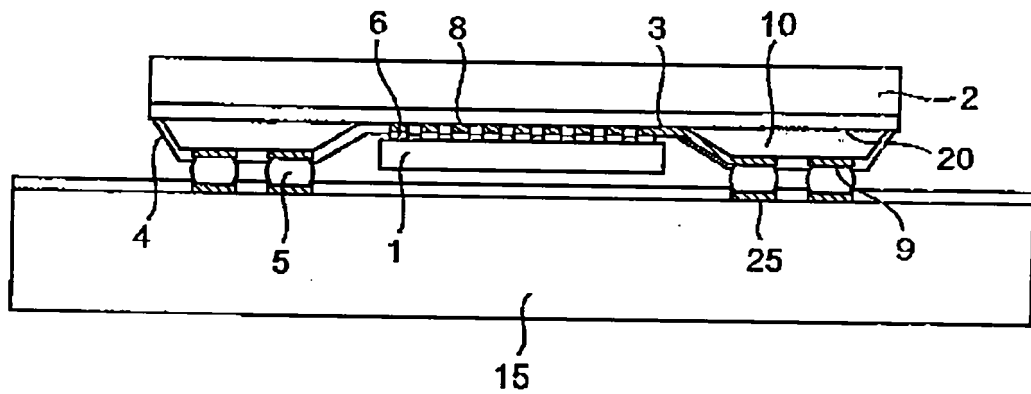


FIG.39A

RELEASED BY
EJECTER PIN

THE STRESS COMPLIANT
LAYER FORMED SILICON
SUBSTRATE

FIG.39B

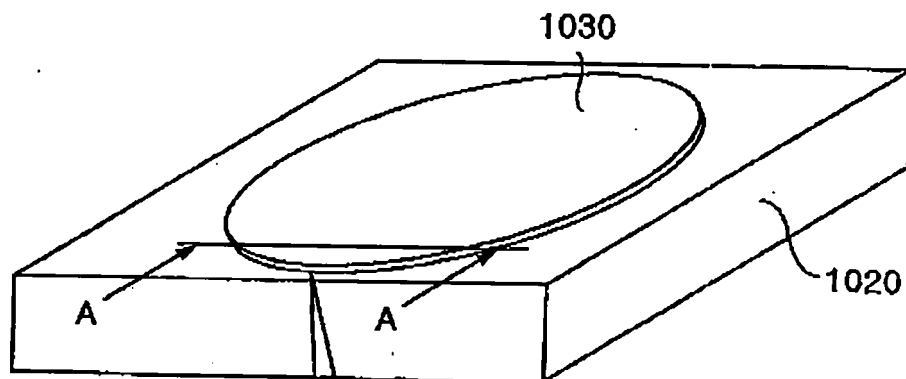


FIG.39C

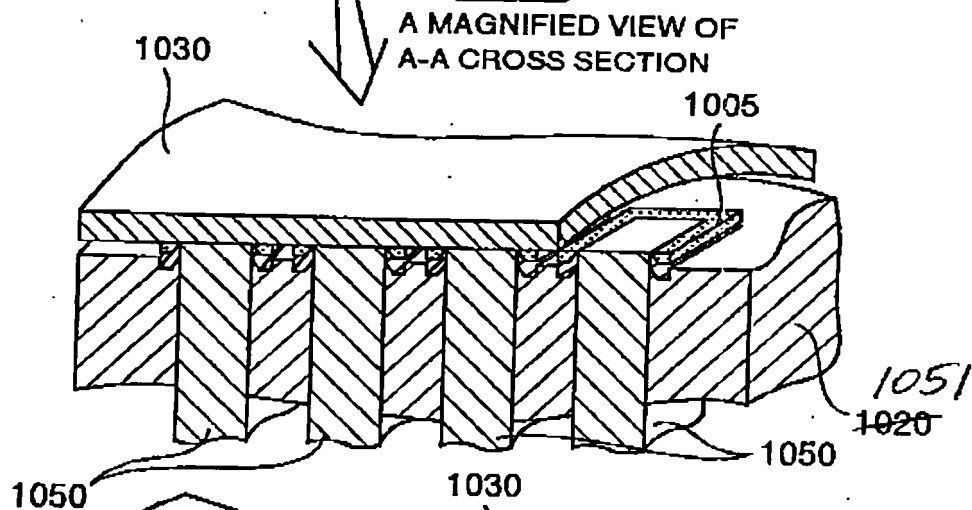
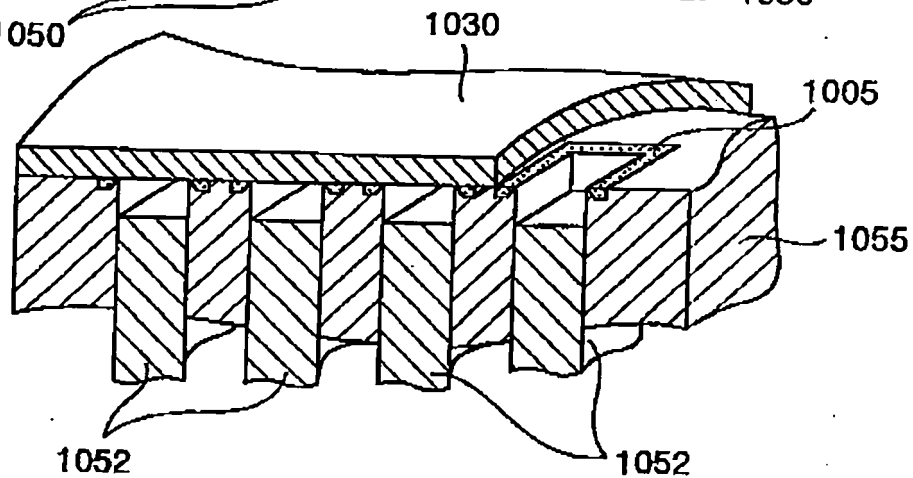


FIG.39D



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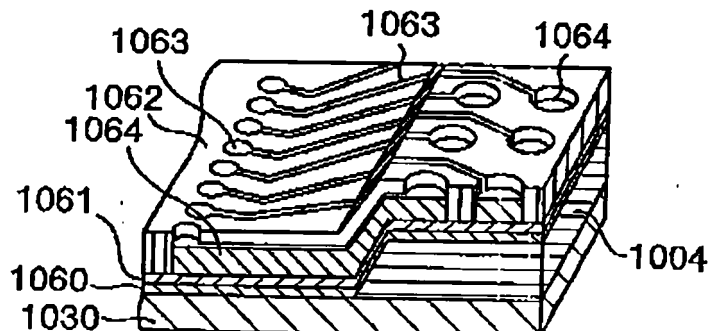
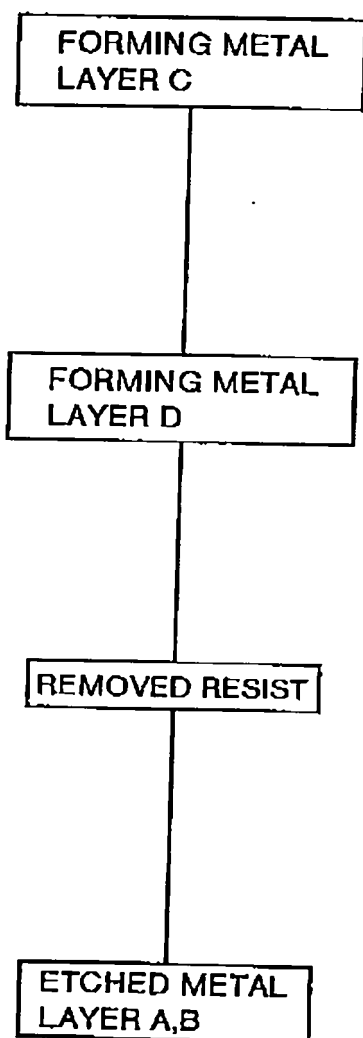


FIG. 42C

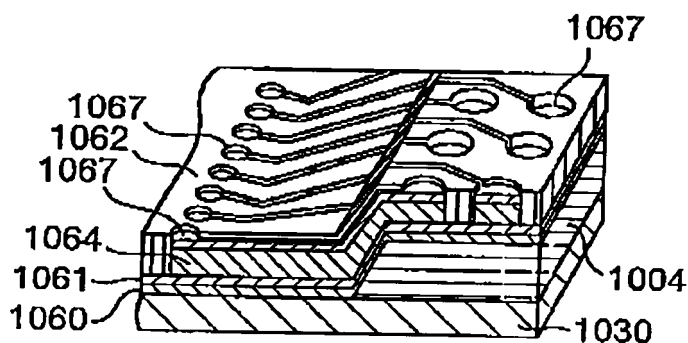


FIG.42D

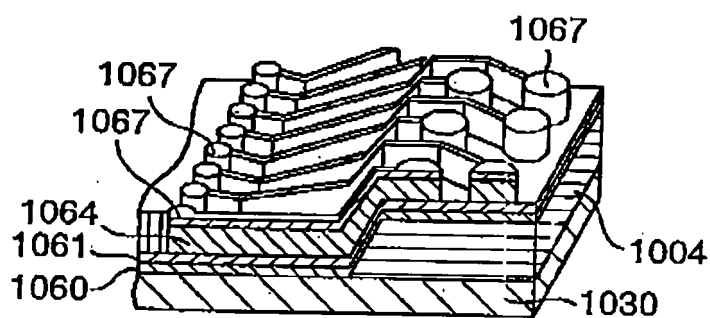


FIG. 42E

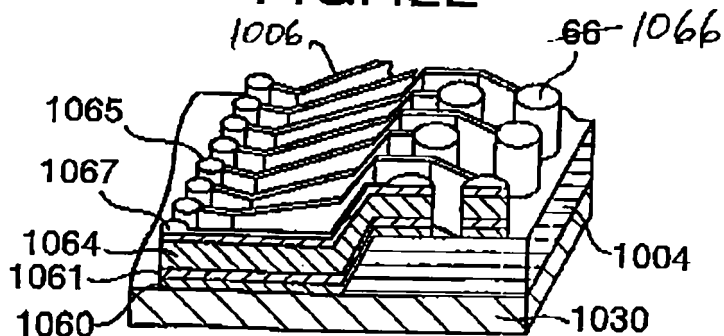


FIG.45A

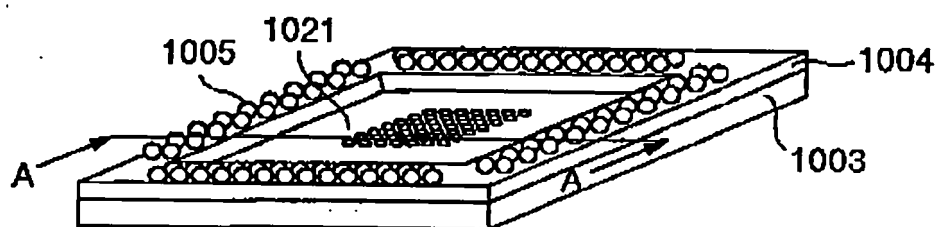


FIG.45B

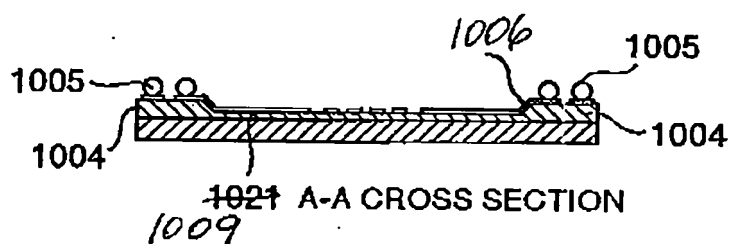


FIG.46A

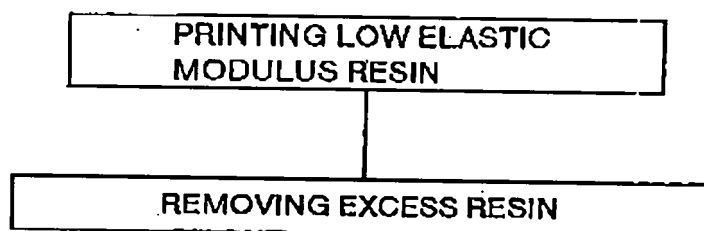


FIG.46B

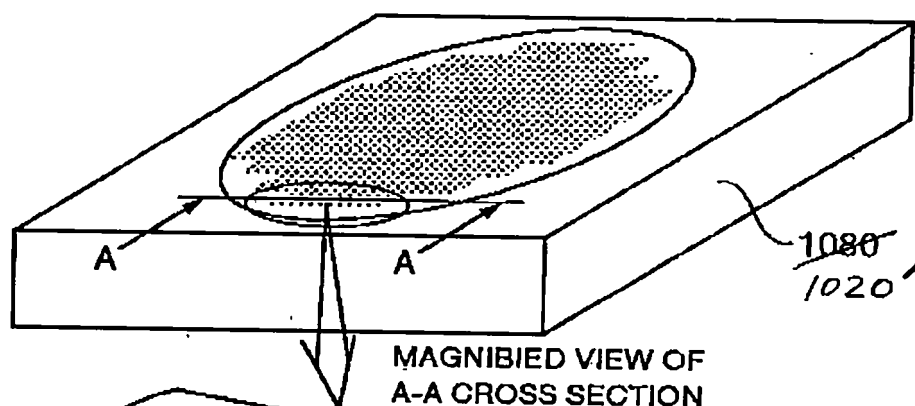


FIG.46C

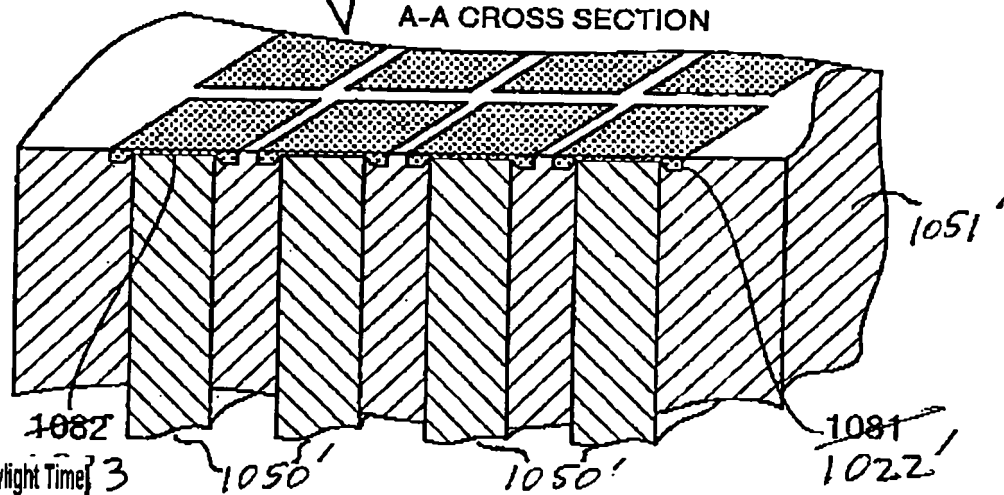


FIG.47A

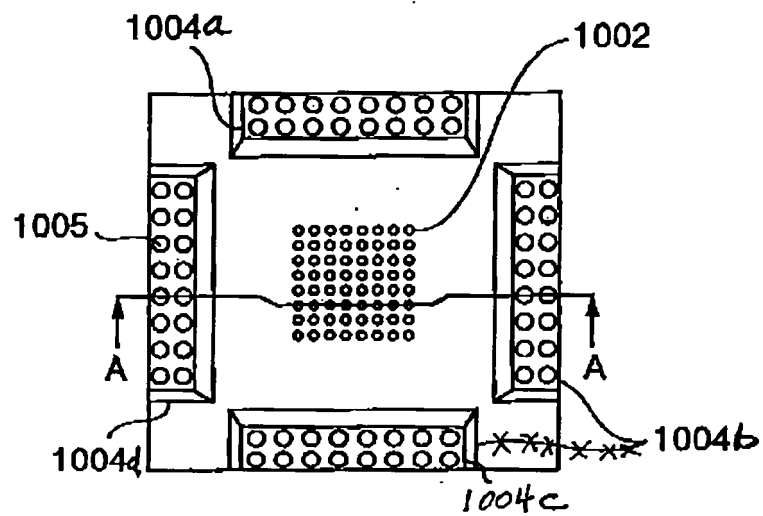


FIG.47B



FIG.48

